3DFR1M

1.0 AMP SURFACE MOUNT FAST RECOVERY RECTIFIERS

VOLTAGE RANGE
1000.0 Volts
CURRENT
1.0 Ampere

FEATURES

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance





MECHANICAL DATA

* Case: Molded plastic
* Lead: Axial leads, solderable per MIL-STD-750, method 2026
* Polarity:Polarity symbols marked on case

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25℃ ambient temperature uniess otherwies specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	3DFR1M	UNITS
Maximum Recurrent Peak Reverse Voltage	1000	V
Maximum RMS Voltage	700	V
Maximum DC Blocking Voltage	1000	V
Maximum Average Forward Rectified Current	1.0	A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	15	A
Maximum Instantaneous Forward Voltage at 1.0A	1.3	V
Maximum DC Reverse Current Ta=25℃	5.0	μA
at Rated DC Blocking Voltage Ta=100℃	100	μA
Maximum Reverse Recovery Time (Note 1)	500	nS
Typical Junction Capacitance (Note 2)	15	pF
Typical Thermal Resistance R JA (Note 3)	80	℃/W
Operating and Storage Temperature Range T_J, T_{STG}	-65 — +150	℃

NOTES:
1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Thermal Resistance from Junction to Ambient.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

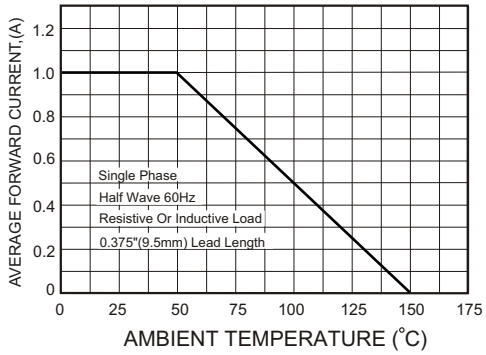


FIG.2-TYPICAL FORWARD CHARACTERISTICS

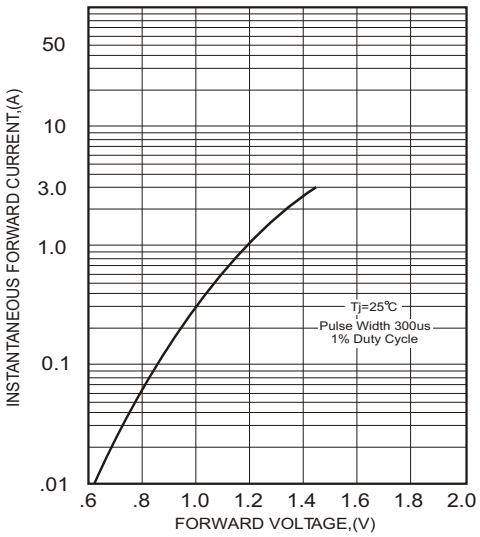
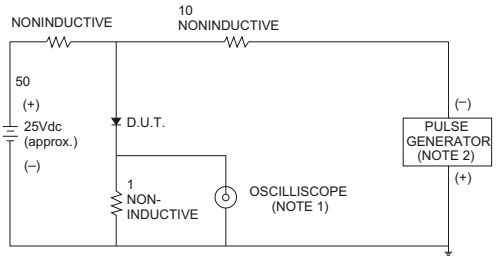
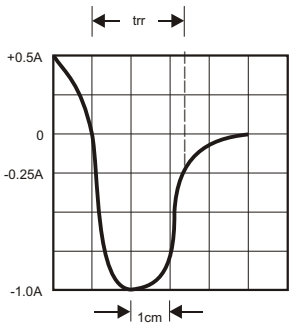


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm.22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.



SET TIME BASE FOR

50 / 10ns / cm

FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

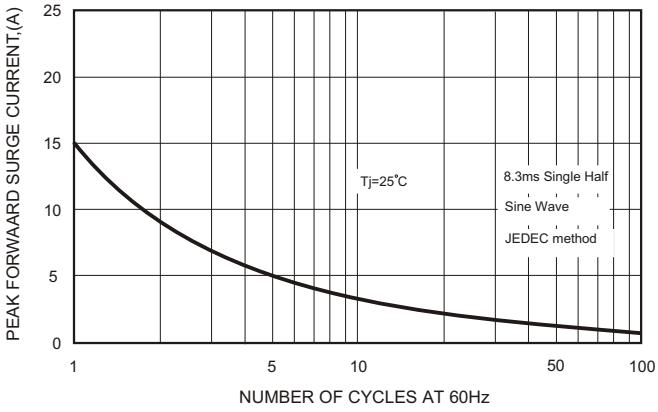


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

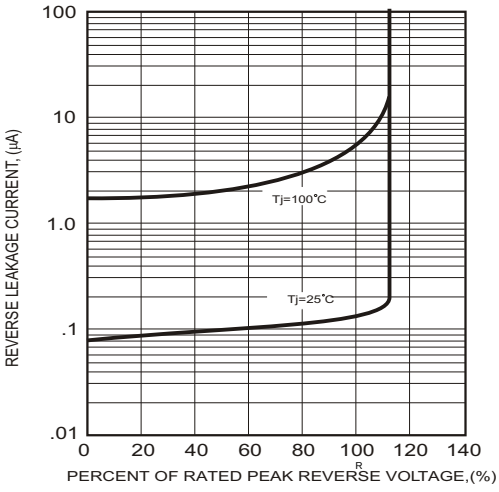
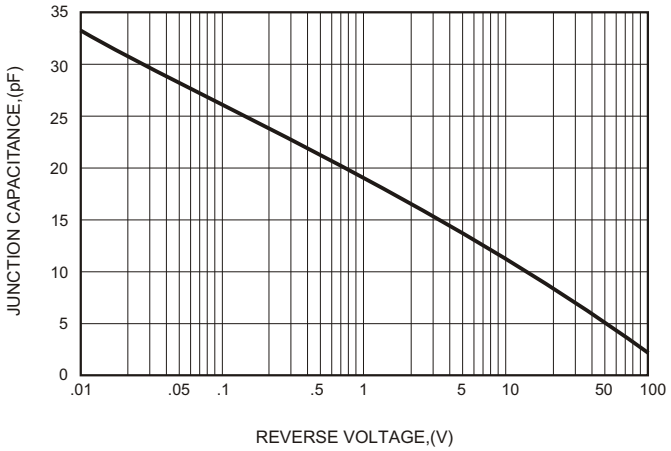


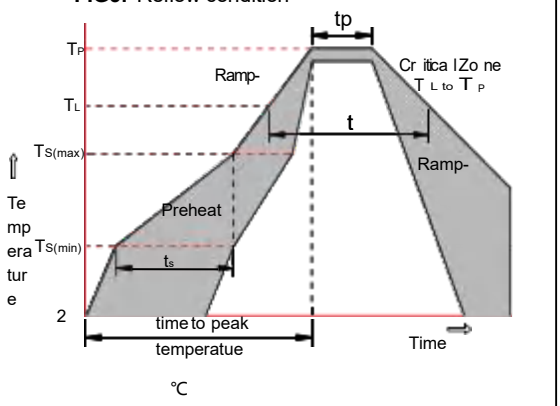
FIG.6-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

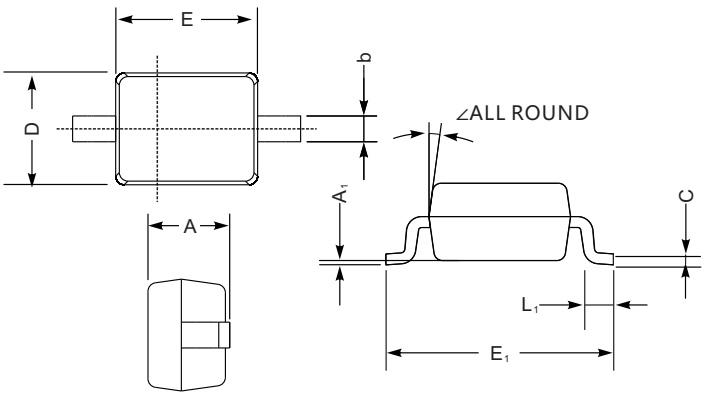
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition



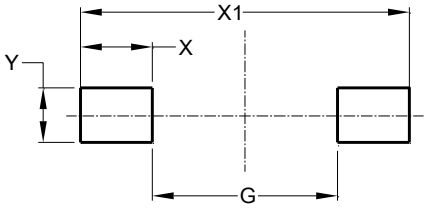
Package Dimensions & Suggested Pad Layout

SOD323



SOD-323 mechanical data

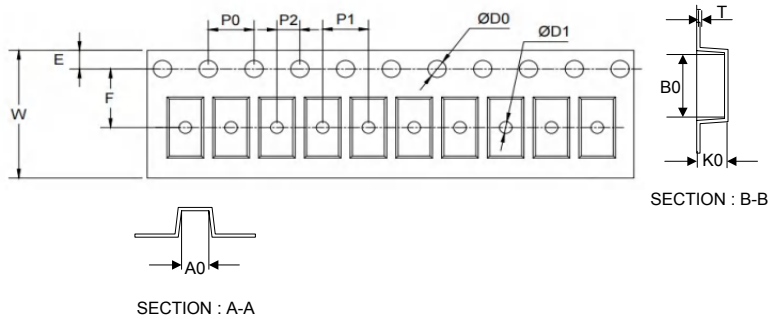
UNIT		A	C	D	E	E_1	b	L_1	A_1	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	



Dimensions	Value (in mm)
G	1.40
X	1.20
X1	3.80
Y	1.00

Tape & rell specification

Tape

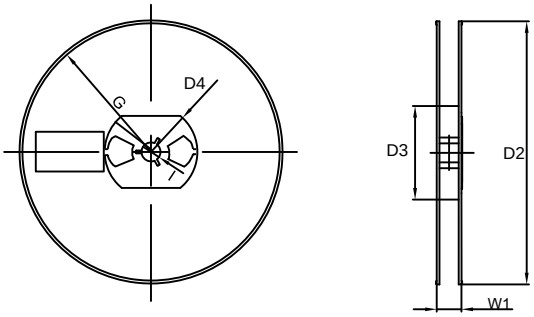


SECTION : A-A

SECTION : B-B

Symbol	Dimension (mm)
P0	4.00±0.20
P1	4.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	1.00±0.20
E	1.55±0.25
F	3.60±0.20
W	8.00±0.20
A0	2.00±0.20
B0	3.25±0.20
K0	1.35±0.20
T	0.23±0.10

7” Reel



D2	177.0±5.0
D3	55Min.
D4	R24.6±2.0
G	R82.0±2.0
I	13.0±2.0
W1	10.20±3.0

Quantity: 3000PCS